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#### COVER NOTE

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From: Secretary-General of the European Commission,  
signed by Mr Jordi AYET PUIGARNAU, Director

date of receipt: 19 November 2018

To: Mr Jeppe TRANHOLM-MIKKELSEN, Secretary-General of the Council of  
the European Union

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No. Cion doc.: C(2018) 7499 final - Annex

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Subject: ANNEX to the Commission Delegated Directive amending, for the  
purposes of adapting to technical progress, Annex III to Directive  
2011/65/EU of the European Parliament and of the Council as regards an  
exemption for lead in solders to complete a viable electrical connection  
between semiconductor die and carrier within integrated circuit flip chip  
packages

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Delegations will find attached document C(2018) 7499 final - Annex.

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Encl.: C(2018) 7499 final - Annex



Brussels, 16.11.2018  
C(2018) 7499 final

ANNEX

ANNEX

to

**Commission Delegated Directive**

**amending, for the purposes of adapting to technical progress, Annex III to Directive 2011/65/EU of the European Parliament and of the Council as regards an exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages**

## ANNEX

In Annex III, entry 15 is replaced by the following:

"15	Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages	Applies to categories 8, 9 and 11 and expires on: <ul style="list-style-type: none"><li>– 21 July 2021 for categories 8 and 9 other than in vitro diagnostic medical devices and industrial monitoring and control instruments;</li><li>– 21 July 2023 for category 8 in vitro diagnostic medical devices;</li><li>– 21 July 2024 for category 9 industrial monitoring and control instruments, and for category 11.</li></ul>
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: <ul style="list-style-type: none"><li>– a semiconductor technology node of 90 nm or larger;</li><li>– a single die of 300 mm<sup>2</sup> or larger in any semiconductor technology node;</li><li>– stacked die packages with die of 300 mm<sup>2</sup> or larger, or silicon interposers of 300 mm<sup>2</sup> or larger.</li></ul>	Applies to categories 1 to 7 and 10 and expires on 21 July 2021."